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PATENT
Attorney Docket No.: 16869P-010700US
Client Ref. No.: 349905249US1

TOWNSEND and TOWNSEND and CREW LLP

By: /George B. F. Yee/

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Kouichi Takahashi, et al.

Application No.: 09/590,897

Filed: June 9, 2000

For: SEALING STRUCTURE FOR
MULTI-CHIP MODULE

Customer No.: 20350

Confirmation No. 1657

Examiner: James M. Mitchell

Technology Center/Art Unit: 2813

POST-ALLOWANCE COMMUNICATION

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

During a review of the file wrapper in connection with a Notice of Allowance mailed December 12, 2008, it was discovered that an IDS filed October 17, 2000 seems not to have been considered. Accordingly, the Office is respectfully requested to consider said IDS.

Respectfully submitted,

/George B. F. Yee/

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